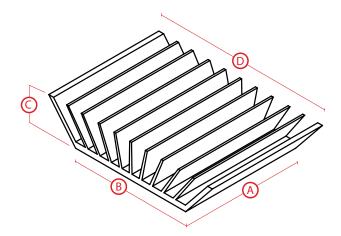


High Performance ASIC Cooling Solutions w/Thermal Tape Attachment

ATS PART # ATS-56007-C4-R0

Features & Benefits

- » maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » Designed specifically for ASIC package and their unique cooling requirements





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AIR VELOCITY		THERMAL RESISTANCE			
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)		
200	1.0	2.4	1.7		
300	1.5	2			
400	2.0	1.7			
500	2.5	1.5			
600	3.0	1.3			
700	3.5	1.2			
800	4.0	1.1			

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
45 mm	45 mm	15 mm	64 mm	SAINT-GOBAIN NO TIM	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

2) Thermal performance data are provided for reference only. Actual performance may vary by application.

ATS reserves the right to update or change its products without notice to improve the design or performance.

4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

Thermal Performance